

Features

- 5050 with integrated high quality constant current IC and RGB LED chip.
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meters
- Data transfer rate of 800 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp.
- SA-I Anti-interference patent technology for single line data transmission.
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

Description

The IN-PI55TBTPRGPB is 5.0*5.0*1.6mm RGB LED with integrated IC. It is a SMD type LED which can be used in various applications.

Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

Package Outline Dimensions & Pin Configuration

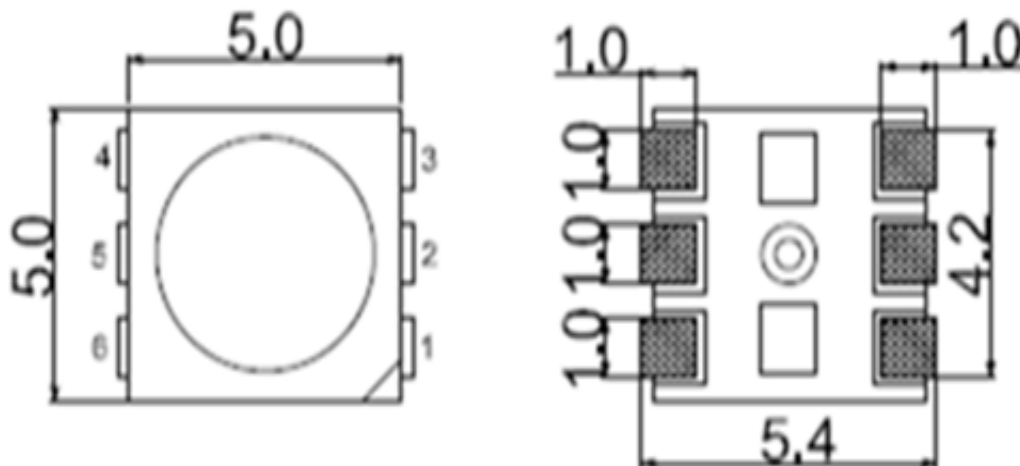


Figure 1. IN-PI55TBTPRGPB Package Outline Dimensions

Pin Configuration

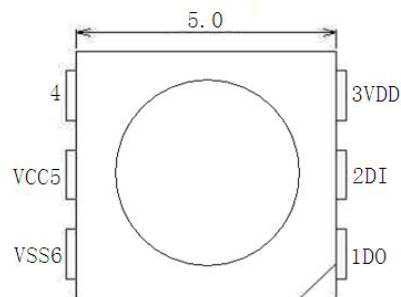


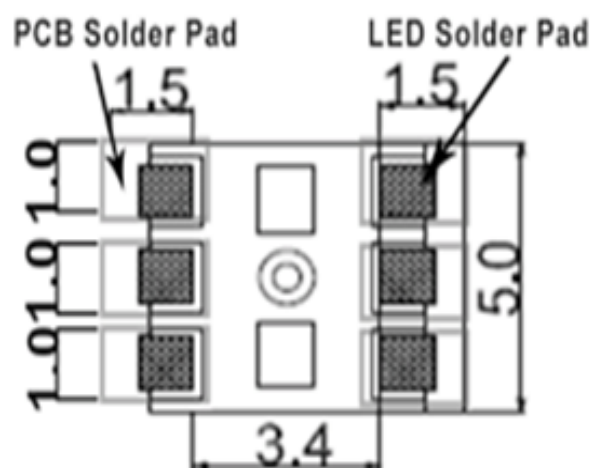
Figure 2. IN-PI55TBTPRGPB Pin Configuration

Notes:

1. Dimension in millimeter, tolerance is $\pm 0.1\text{mm}$ unless otherwise noted.

Number	Symbol	Function Description
1	DO	Display data cascaded output (800k bps)
2	DI	Display data cascaded input (800k bps)
3	VDD	Power Supply
4		NC
5	VCC	Power supply
6	VSS	Ground

Soldering Pad Size



Absolute Maximum Rating ($T_a = 25\text{ }^{\circ}\text{C}$, $V_{SS}=0V$)

Parameter	Symbol	Range	Unit
Logic supply voltage	V_{DD}	+3.5~+5.5	V
Logic input voltage	V_{IN}	-0.5 ~ $V_{DD}+0.5$	V
Operating temperature	T_{OPT}	-45 ~ +85	$^{\circ}\text{C}$
Storage temperature	T_{STG}	-50 ~ +150	$^{\circ}\text{C}$
ESD pressure(HBM)	V_{ESD}	4K	V
ESD pressure(DM)	V_{ESD}	200	V

LED Characteristics ($T_a = 25^{\circ}\text{C}$)

 ($T_a=-25^{\circ}\text{C}$, unless otherwise specified)

Light color	Wavelength (nm)	Light intensity (mcd)	Working current (mA)	Working voltage (V)
R	620-625	400-700	12	1.8-2.2
G	520-525	1000-1500	12	2.8-3.2
B	465-470	200-400	12	2.8-3.2

Recommended Operating Ranges (unless otherwise specified, $T_A = -20 \sim +70\text{ }^{\circ}\text{C}$, $V_{DD} = 4.5 \sim 5.5\text{V}$, $V_{SS} = 0\text{V}$)

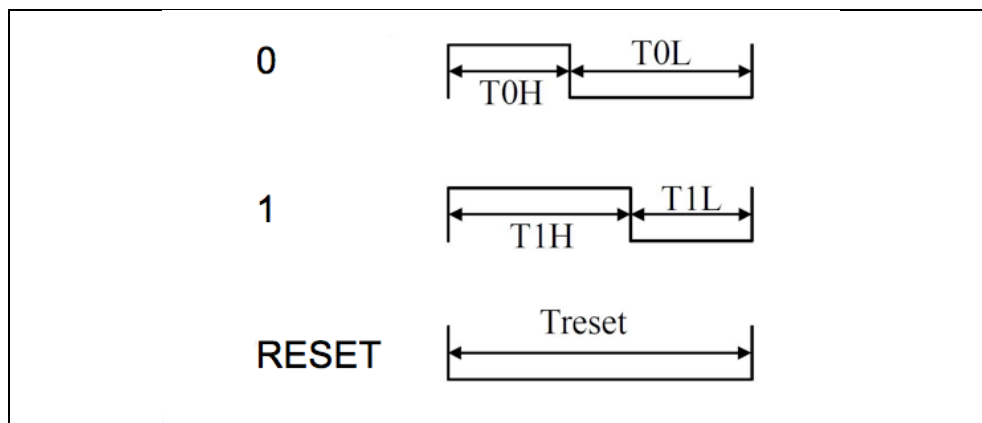
Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
Supply voltage	V_{DD}	-	5.2	-	V	-
R/G/B port pressure	$V_{DS, MAX}$	-	-	26	V	-
DOUT drive capability	I_{DOH}	-	49	-	mA	maximum source current
DOUT drive capability	I_{DOL}	-	-50	-	mA	maximum sink current
High level input voltage	V_{IH}	3.4	-		V	$V_{DD} = 5.0\text{V}$
Low level input voltage	V_{IL}	-	-	1.6	V	$V_{DD} = 5.0\text{V}$
The frequency of PWM	F_{PWM}	-	1.2	-	KHZ	-
Static power consumption	I_{DD}	-	1	-	mA	-

Switching Characteristics (unless otherwise specified, TA=25 °C)

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
The speed of data transmission	f_{DIN}	-	800	-	KHZ	The duty ratio of 67% (data 1)
DOUT transmission delay	T_{PLH}	-	-	500	ns	DIN→DOUT
	T_{PHL}	-	-	500	ns	
I_{OUT} Rise/Drop Time	T_r	-	100	-	ns	VDS=1.5 $I_{OUT}=5/13mA$
	T_f	-	100	-	ns	

Timing Waveforms

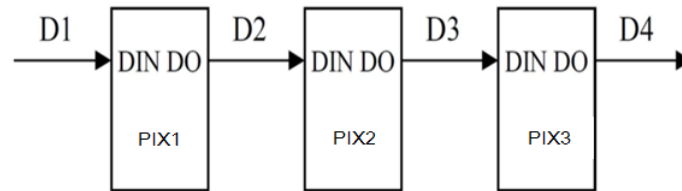
1. Input Code



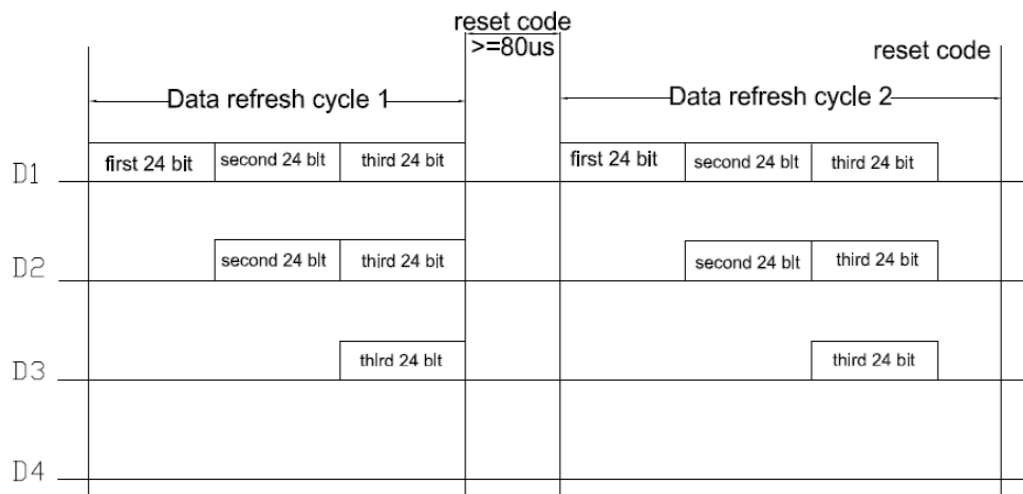
2. The data transmission time ($T_H+T_L=1.25\mu s\pm 600ns$):

Name	Description	Typ. value	error
T0H	0 code, high level time	0.3 μs	$\pm 0.15\mu s$
T0L	0 code, low level time	0.6 μs	$\pm 0.15\mu s$
T1H	1 code, high level time	0.9 μs	$\pm 0.15\mu s$
T1L	1 code, low level time	0.6 μs	$\pm 0.15\mu s$
Trst	Reset code, low level time	80 μs	

3. Connection Scheme



4. Data Transfer Format



Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

5. 24-bit data format



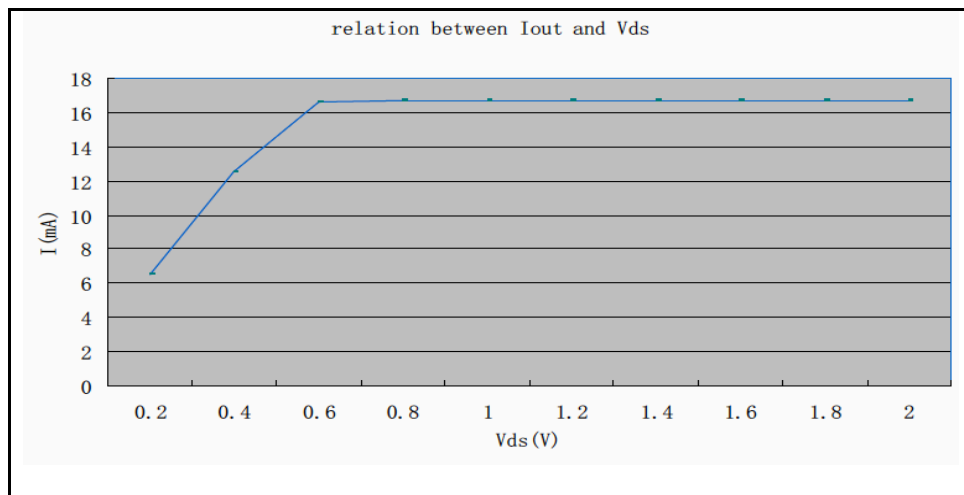
Note: The data is sent in the sequence of GRB, and the MSB is sent first.

Constant Current Characteristic

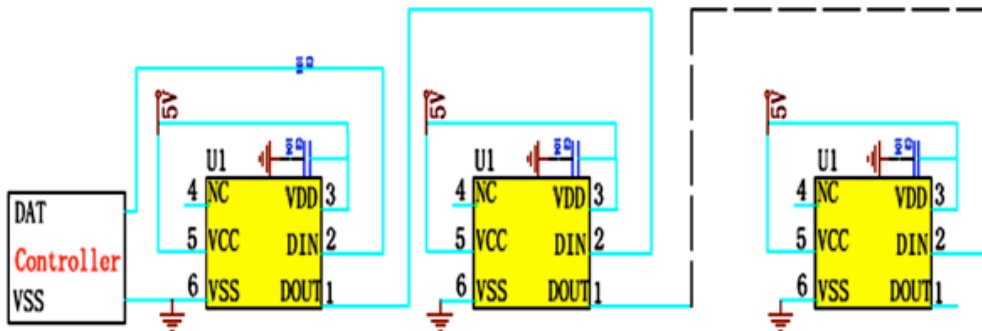
With excellent constant current characteristics,

- (1) The differences of current between Channel is less than $\pm 1.5\%$
- (2) The differences of current between Chip is less than $\pm 3\%$
- (3) When the voltage of the load change, the output current is not affected, as shown in the figure below
- (4) Below output port of the current I_{out} and add on the port voltage V_{ds} curve relationship.

The smaller the I_{out} current, the smaller in the condition of constant current need of V_{ds} .



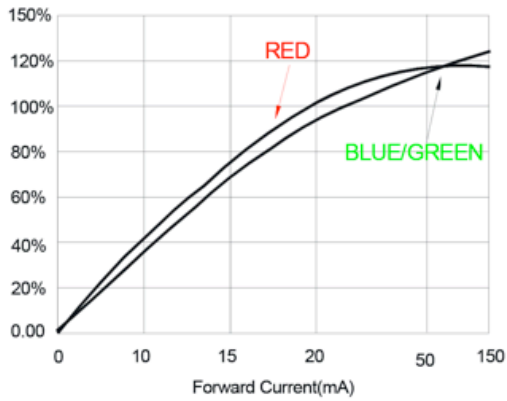
Typical Application Circuit



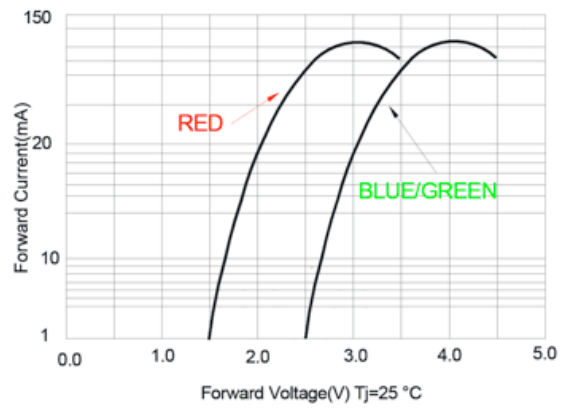
Product signal input and output must be connected in series with protection resistor R_1 . R_1 depends on the size of the cascade amount, the greater the number of cascade, the smaller R_1 . The general recommended value is between 200-2K Ω , usually the recommended value is typical 500 Ω .

LED Performance Graph

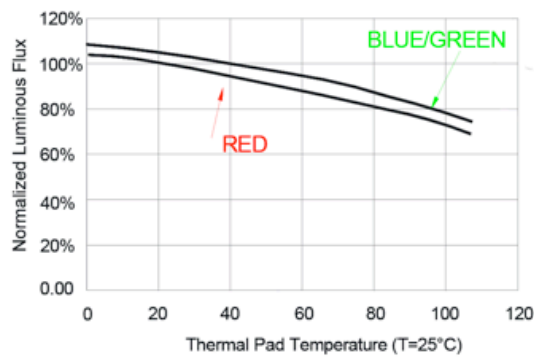
Typical Relative Luminous Flux vs. Forward Current



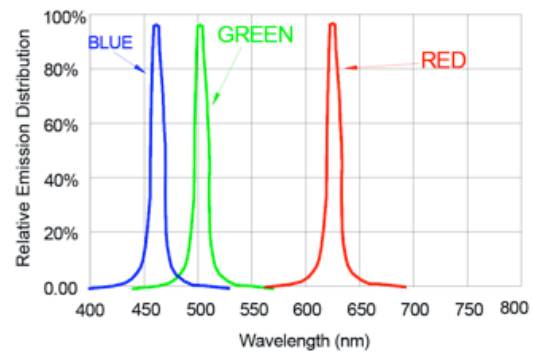
Forward Voltage vs. Forward Current



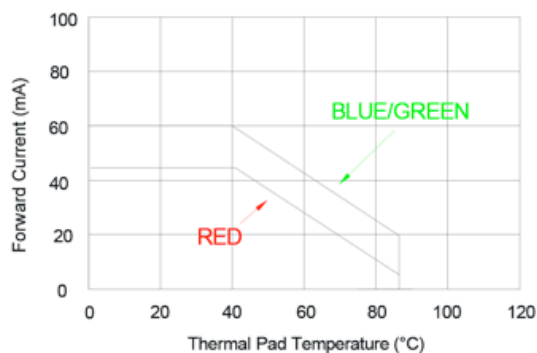
Thermal Pad Temperature vs. Relative Light Output



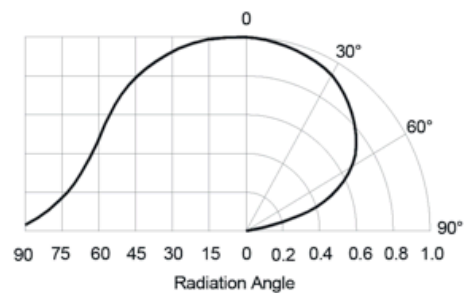
Wavelength Characteristics



Thermal Pad Temperature vs. Forward Current





Typical Radiation Pattern 120°



Ordering Information

Product	Emission Color	IV(mcd)	Orderable Part Number
IN-PI55TBTPRPGPB	R	400-700	IN-PI55TBTPRPGPB
	G	1000-1500	
	B	200-400	

Label Specifications

 Inolux			Date: yyyy/mm/dd
CUSTOMER P/N: 			
INOLUX P/N: 		QTY: PCS 	
LOT NO: 		QC	
IV BIN:	COLOR BIN:	VF:	

Inolux P/N:

I	N	PI	-	55	T	B	T	(X)	R	(X)	G	(X)	B	-	X	X	X	X
Inolux		Product		Package	Die Qty.	Variation	Orientation	Current	Color	Current	Color	Current	Color		Customized Stamp-off			
		PI- Single trace IC PC- Clock Function IC		55TB = 5.0 x 5.0 x 1.6 mm (6 pins)			T = Top Mount	P=12mA	R = 624 nm	P=12mA	G = 520 nm	P=12mA	B = 470 nm					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018,)				Month	Date	Serial

Precautions

Please read the following notes before using the product:

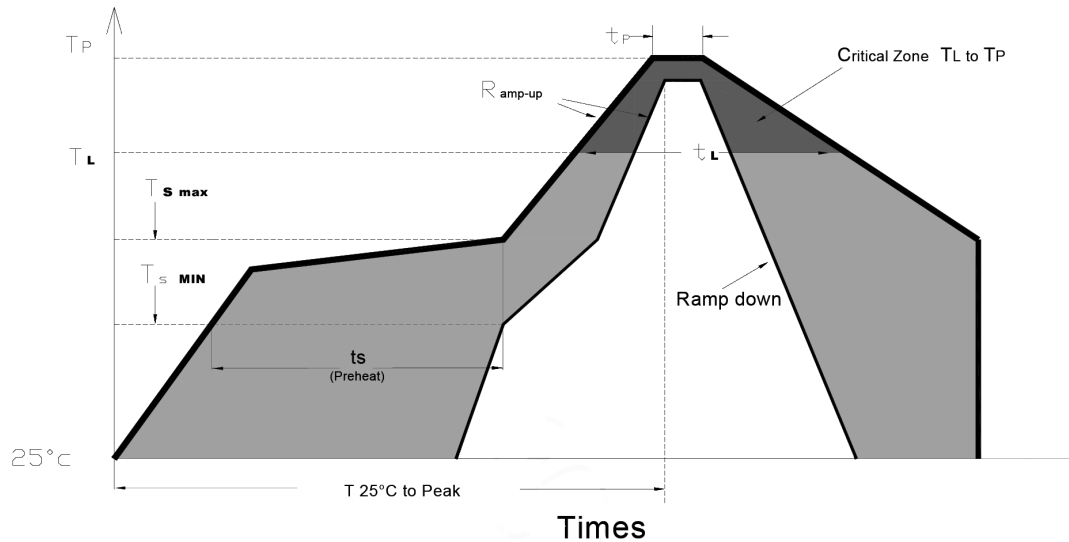
1. Storage

- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.
- 1.4 After opening the package, the remaining LEDs should be kept in a resealed bag.
- 1.5 The LEDs require mandatory baking before usage. Baking treatment listed below.
- 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

*Baking treatment: 60±5°C for 24 hours.

2. Soldering Condition

Recommended soldering conditions:



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate ($T_{s \max}$ to T_p)	3°C/second max.
Preheat: Temperature Min ($T_{s \min}$)	150°C
Preheat: Temperature Min ($T_{s \max}$)	200°C
Preheat: Time ($t_{s \min}$ to $t_{s \max}$)	60-180 seconds
Time Maintained Above: Temperature (T_L)	217 °C
Time Maintained Above: Time (t_L)	60-150 seconds
Peak/Classification Temperature (T_p)	240 °C
Time Within 5°C of Actual Peak Temperature (t_p)	<10 seconds
Ramp-Down Rate	6°C/second max.
Time 25 °C to Peak Temperature	<6 minutes max.

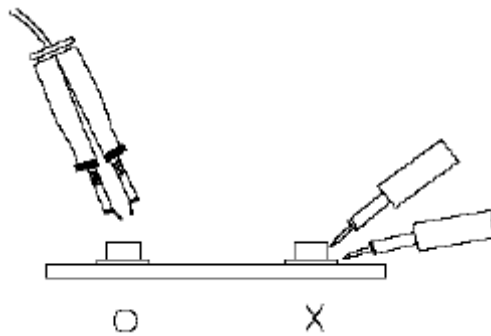
Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-31-2018
Format Adjustment		1.1	07-01-2018
Update intensity level		1.2	01-08-2019
Revise precautions	10	1.1	07-31-2019

DISCLAIMER

INOLUX reserves the right to make changes without further notice to any products herein to improve reliability, function or design. INOLUX does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

LIFE SUPPORT POLICY

INOLUX's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of INOLUX or INOLUX CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Inolux:

[IN-PI55TBTPRPGPB](#)